



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20130913002
TL331-Q1 data sheet - CMS C1308059
Information Only**

Date: 9/17/2013
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a specification for a device that is currently offered by Texas Instruments.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130913002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TL331QDBVRQ1	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130913002			PCN Date:	09/17/2013
Title:	TL331-Q1 data sheet - CMS C1308059				
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037	Dept:	Quality Services
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>	Part number change			
PCN Details					
Description of Change:					
<p>Texas Instruments publication SLVS969 has changed as described below:</p> <p>Page 3 Added a Thermal Information table</p> <p>Page 3 Changed VICR in the Electrical Characteristics table</p> <p>Page 3 Changed test conditions of IOL in the Electrical Characteristics table</p>					
Reason for Change:					
Correct the test conditions.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There is no change to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
TL331QDBVRQ1 TL331IDBVRQ1					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com